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Presentation at the Universitaet zu Darmstadt, Germany
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Jet Propulsion Laboratory, Pasadena California USA





JPL's Aerogel Named World's Lightest Solid



A. seeter: http://www.jpl.nasa.gov/index.html

A new version of aerogel, the particle-collecting substance on NASA's Stardust spacecraft, has been recognized by Guinness World Records as the solid with the lowest density.

Stardust home page

Global Surveyor Adds to its Martian Photo Album



A view of the red planet almost completely enveloped in dust storms is one of 15,251 newly released images from NASA's Mars Global Surveyor.

More Mars images

Spotlight: Wiring Future Fashion Trend



Looking for the ultimate accessory? Someday, you might be able to wear your computer. JPL engineer Ann Devereaux is hard at work developing the Wearable Augmented Reality Prototype (Warp), a personal communication device.

Browse Image

Aqua carries atmosphere instrument into orbit



NASA's latest Earth observing satellite, Aqua, carrying the NASA Jet Propulsion Laboratory-managed Atmospheric Infrared Sounder instrument, successfully launched early Saturday, May 4. Aqua is dedicated to advancing our understanding of Earth's water cycle and our environment.



Upcoming Lecture:



Open House update:

JPL will not be holding Open House in May

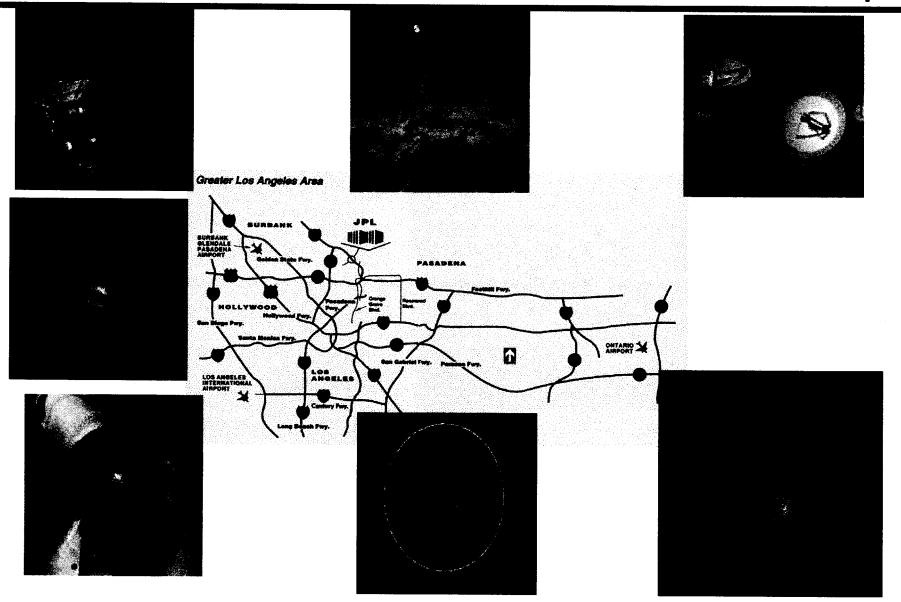
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OUTLINE

- Motivation
- Frequency multiplier chains
- ◆ Devices used for the frequency multipliers
- Simulations and diode model
- ◆ Technology flowchart of GaAs Monolithic Membrane Diode (MoMeD) Circuits
- ♦ Low frequency designs
- High frequency designs
- Measurements on reliability
- ◆ Discussion





Motivation

Development of components for space-based heterodyne sensor technology at mm and submillimeter wavelengths

<u>for</u>

Astrophysics, Earth and Planetary Heterodyne Remote Sensing Instruments (Herschel Space Observatory, EOS-MLS, ROSETTA).

High-resolution spectroscopy of molecular species

HD (1-0) transition line at 112μm to determine H/D ratio
High resolution spectroscopy: CII and NII hyperfine structure chemistry in
InterStellar Medium (ISM)

Specific Technology Goal

Fabrication of GaAs based circuits at JPL

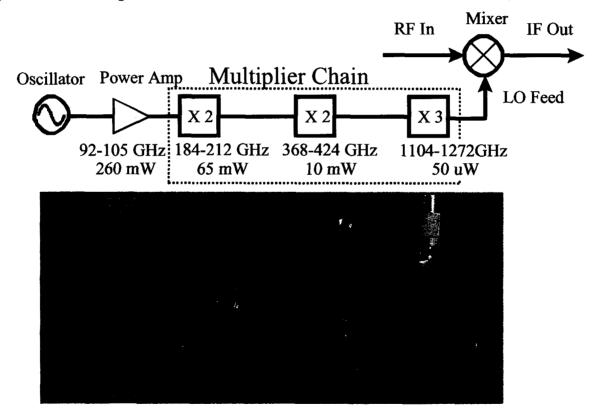
- -Low frequency circuits (< 1THz) with reduced substrate
- -High frequency circuits (>1THz) with an monolithic membrane diode (MoMeD)





Frequency multiplier chain up to 3THz

Example: Power amplifier module, 200GHz and 400GHz doubler, 1200GHz tripler







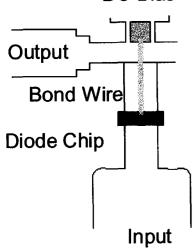
- ◆ Ruggedness, resistance to shock and vibration for space qualification.
- ◆ Wide bandwidth (10 to 14 %).
- ♦ High power capability (200 250 mW).
- ◆ High efficiency for multiple cascaded stages.
- ◆ Improved performance at low temperatures.



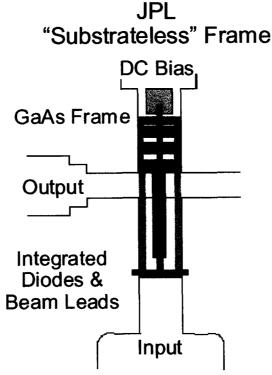


Planar Balanced Doubler Technologies Fabricated at JPL

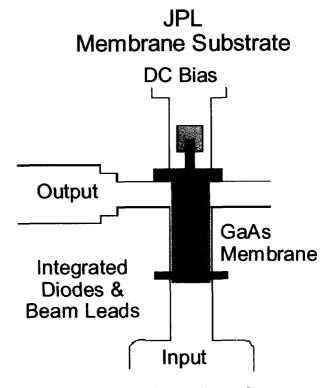
University of Massachusetts Discrete DC Bias



- ! Chip soldered to block
- ! Bondwire connects chip to DC Bias Cap



- ! All chip connections to block made with beam leads
- ! Diodes integrated into circuit
- ! GaAs under metal removed for low loss



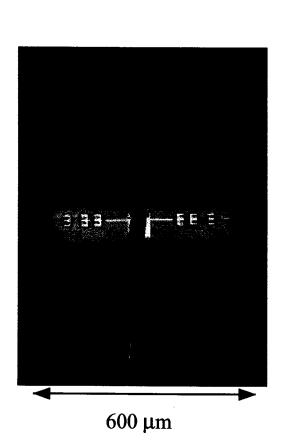
- ! Circuit fabricated on 3 mm GaAs membrane
- ! Block connections made with beam leads



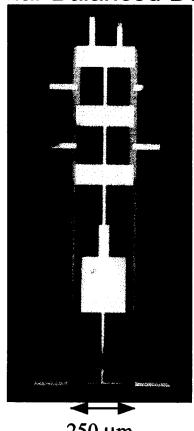




Photos of Planar Balanced Doubler Types



Discrete



 $250\;\mu m$

20KU

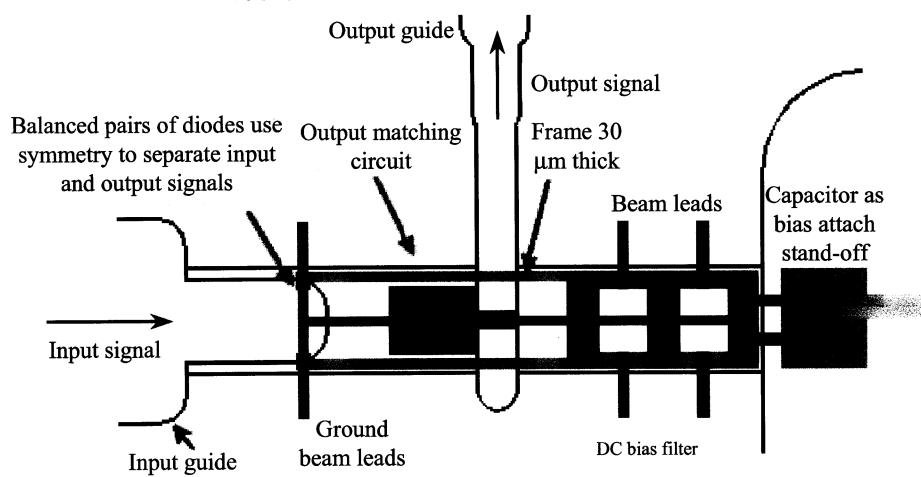
Monolithic substrateless

Monolothic membrane





400 GHz Substrateless Circuit in Block

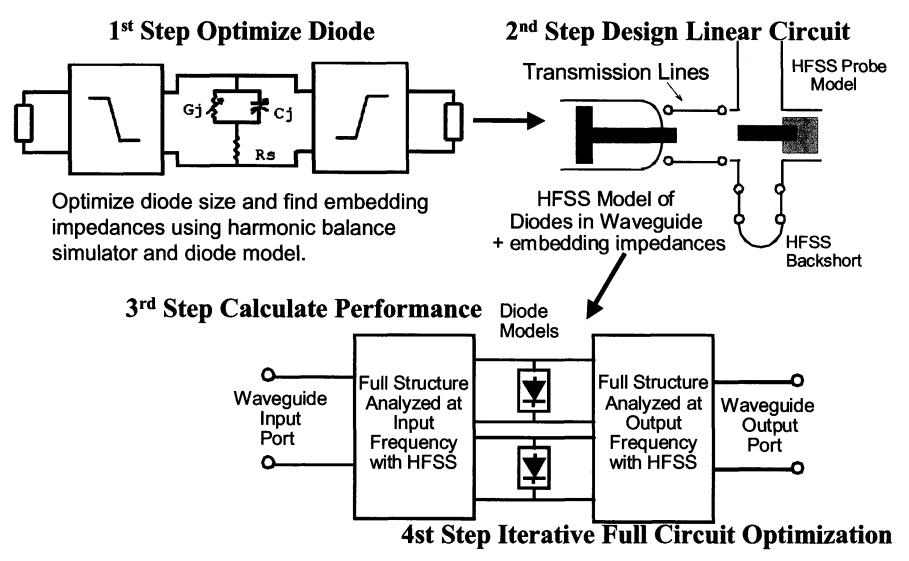


Length: 1.5 mm



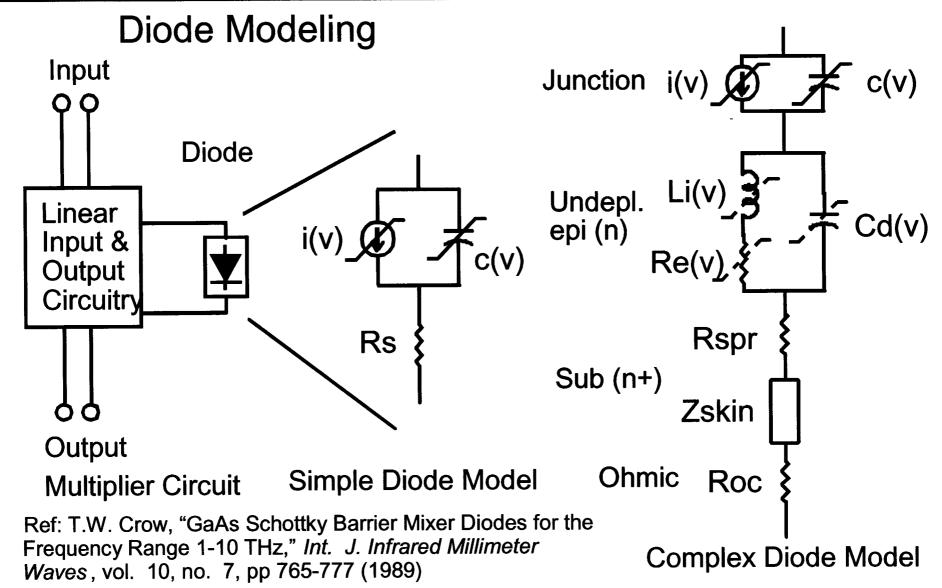


Three-Step Doubler Design Strategy





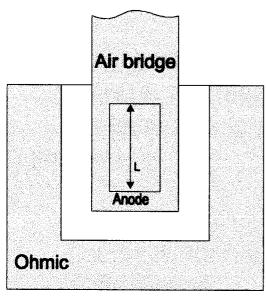


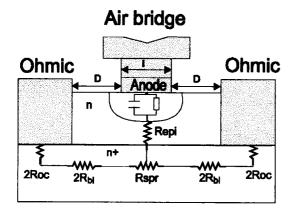


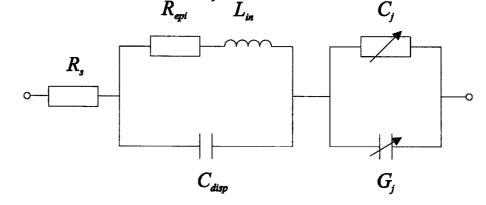




JPL Schottky diode model, cont'd







$$C_{j} = \frac{Ll.\varepsilon_{s}}{W} \left(1 + 4D_{1} \frac{(L+l)W}{Ll} \right) = \frac{A\varepsilon_{s}}{W} \gamma_{c} \qquad I_{m} = AN_{d}qv_{m}\gamma_{c}$$

$$R_{epi} = \rho_{epi} \times \frac{t_{epi} - W}{l \times L} \times \gamma_r$$

$$R_{spr} = \rho_{spr} \times \frac{l}{12 \times L}$$
 $R_{oc} = \frac{\sqrt{\frac{\rho_{oc} \times \rho_{bl}}{t_{bl}}}}{2 \times L}$

$$R_{epi} = \rho_{epi} \times \frac{t_{epi} - W}{l \times L} \times \gamma_r \qquad R_{bl} = \rho_{bl} \times \frac{D}{(2 \times L + l) \times t_{bl}}$$

$$R_{oc} = \frac{\sqrt{\frac{\rho_{oc} \times \rho_{bl}}{t_{bl}}}}{2 \times L + L}$$





JPL Schottky diode model

Includes:

Electron velocity saturation

Breakdown

Edge effects

Temperature dependency of electron mobility

Some frequency dependency of the R_s (skin effect in n⁺)

As a function of:

Junction size (L,I)

Epilayer thickness and doping (t_{epi}, N_d)

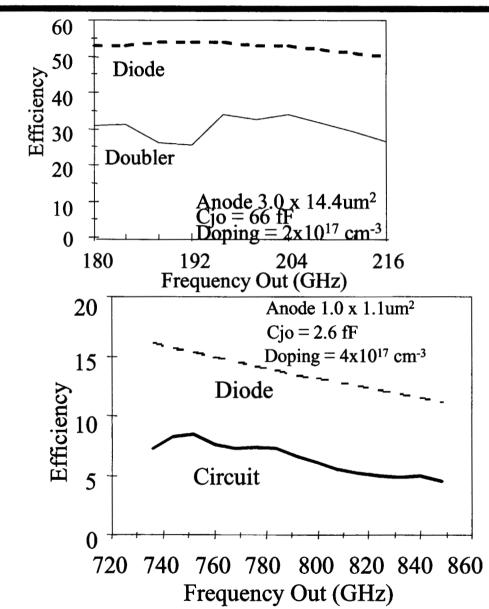
Temperature (T)

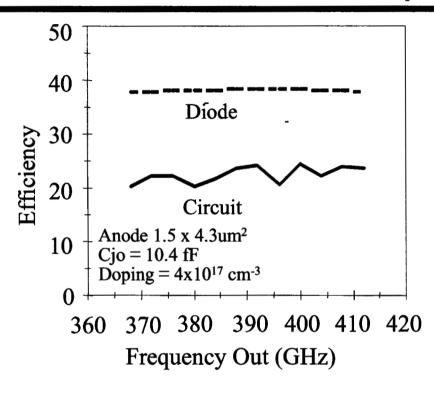
Allows:

optimization of the diode parameters (L,I,Nd) for given frequency and power to maximize multiplier efficiency.



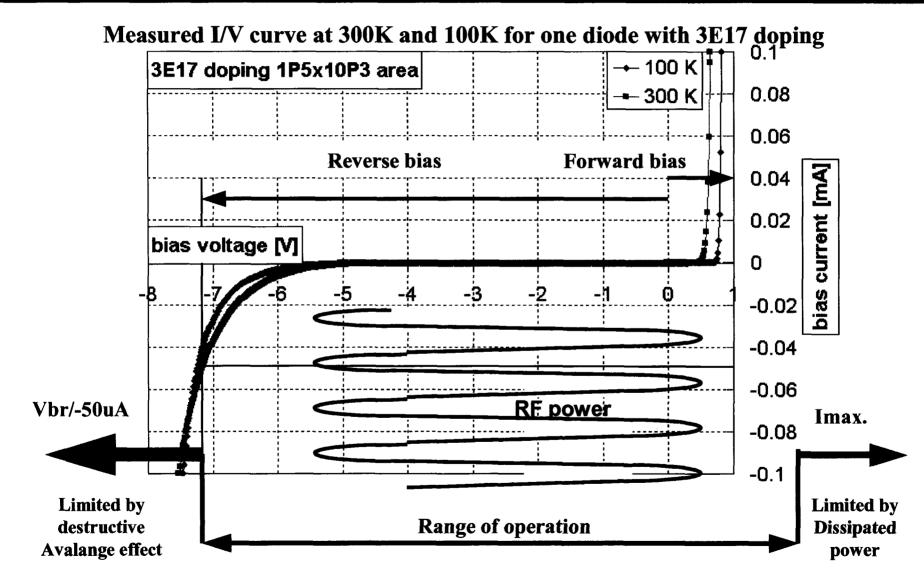






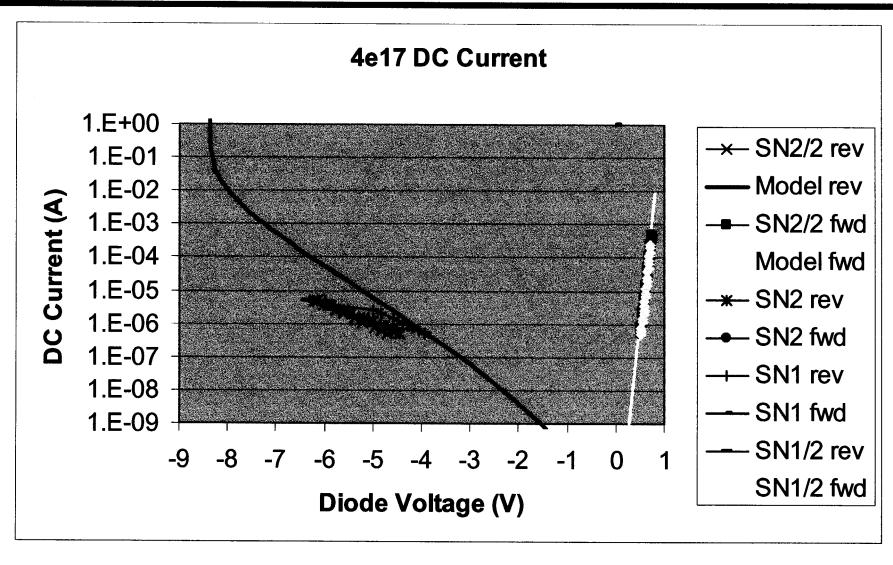








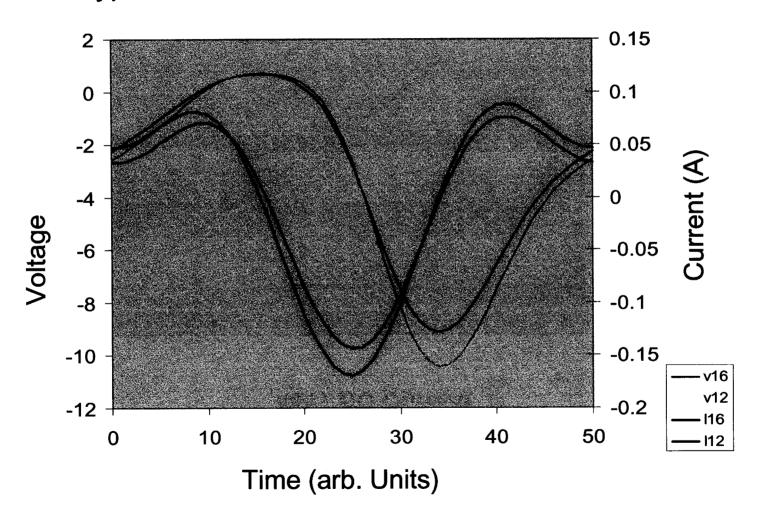








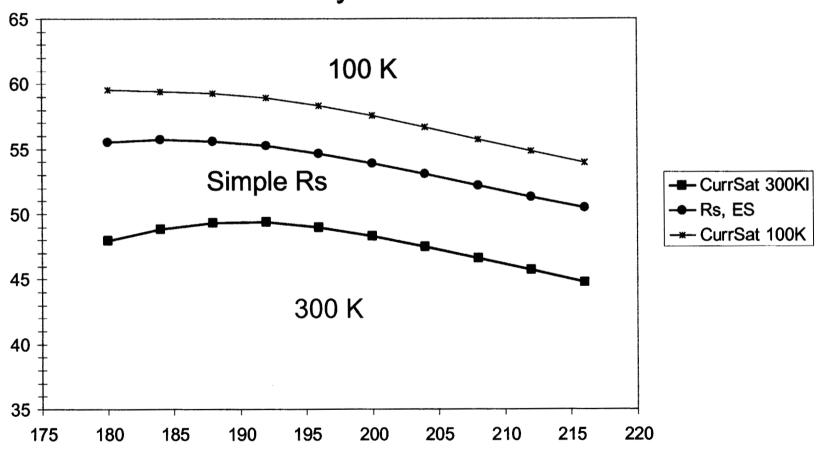
Typical Waveforms for Two Diode Sizes







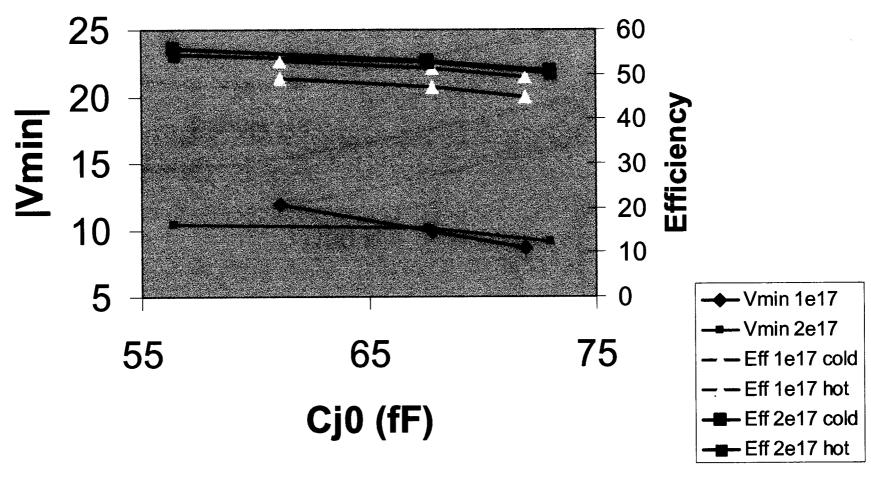
Low-Temperature, High Temperature and Simple Model Diode Efficiency Prediction for Same Circuit







Effect of Temperature and Doping on Efficiency and Voltage Peaks

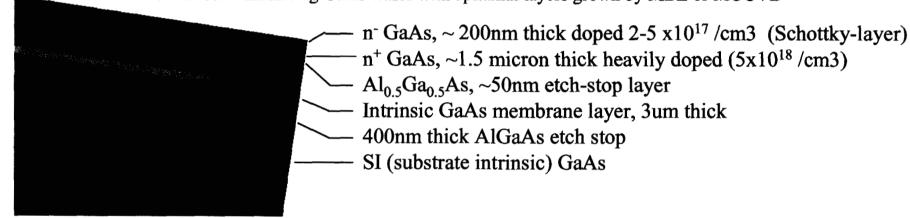


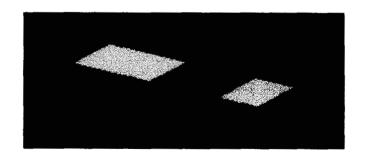




Technology flowchart of GaAs Monolithic Membrane Diode (MoMeD) Circuits,

Material: semi-insulating GaAs wafer with epitaxial layers grown by MBE or MOCVD



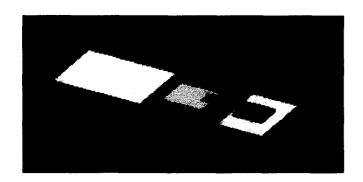


- recessed Ohmic contacts into the n+ GaAs layer, alloyed Au/Ge/Ni/Ag/Au metalization
 Mesa definition by selective dry etch of BCl3,
- •Mesa definition by selective dry etch of BCl3, SF6, and Ar in an electron cyclotron resonance (ECR) reactive ion-etch system (RIE)
- •Interconnect metal (gold)



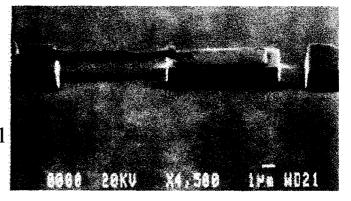


Technology flowchart of GaAs Monolithic Membrane Diode (MoMeD) Circuits



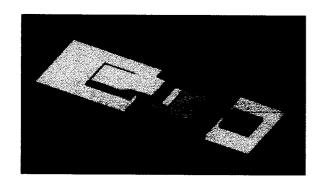
•E-beam anode

A second layer of patterned photoresist provides the stencil for the Ti/Pt/Au Schottky and interconnect metal.



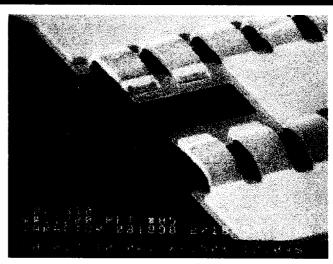




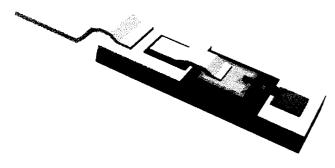




- •SiN, silicon nitride is deposited using plasma enhanced chemical vapor deposition (PECVD), isolator for MIM capacitors
- Bridge/capacitor metal
- •Membrane definition
- •Bridge metal/RF probe/ beam leads



Rectangular Schottky diode



•substrate removed, GaAs substrate is thinned to the desired thickness (12-50 mm) by lapping, polishing and wet etching •circuits are separated and can be removed from the carrier wafer by dissolving the mounting wax and collecting the chips on filter paper





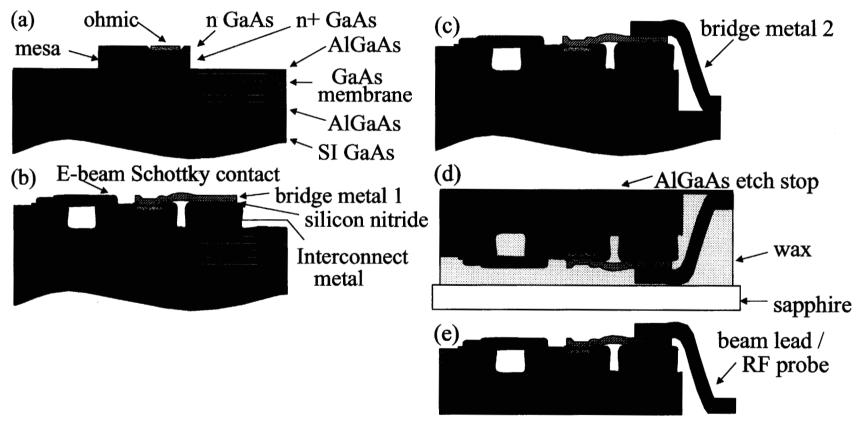


Fig. 2 High Frequency process. (a) Ohmic and mesa definition. (b)_ Interconnect metal and e-beam-defined Schottky deposition, followed by passivation and bridge metal 1 definition. (c) Membrane layer etch and bridge metal 2 deposition. (d) Removal of substrate with selective etch. (e) Release of device from carrier wafer.





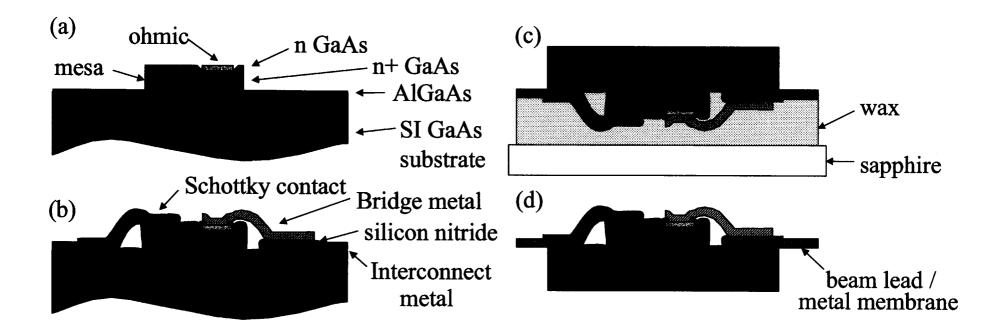
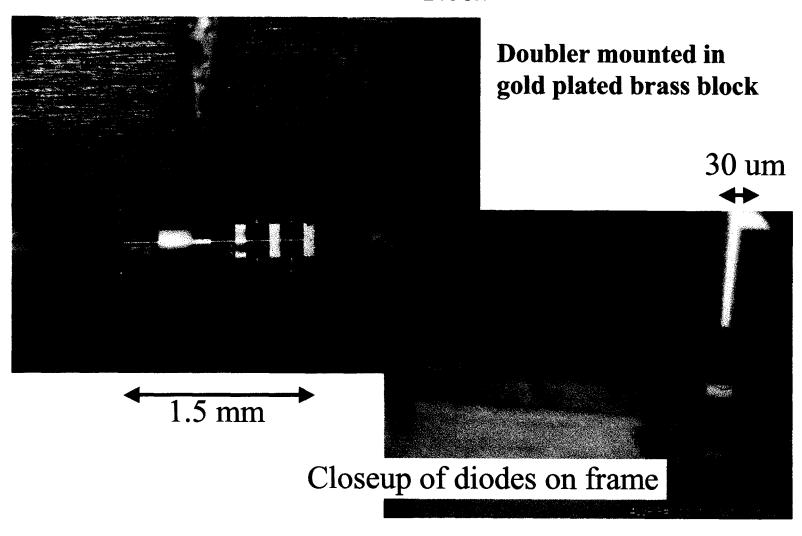


Fig. 1 Low Frequency process. (a) Ohmic and mesa definition. (b) Interconnect metal and air-bridged Schottky deposition, followed by passivation and bridge metal definition. (c) Backside thinning and device separation. (d) Release of device from carrier wafer.





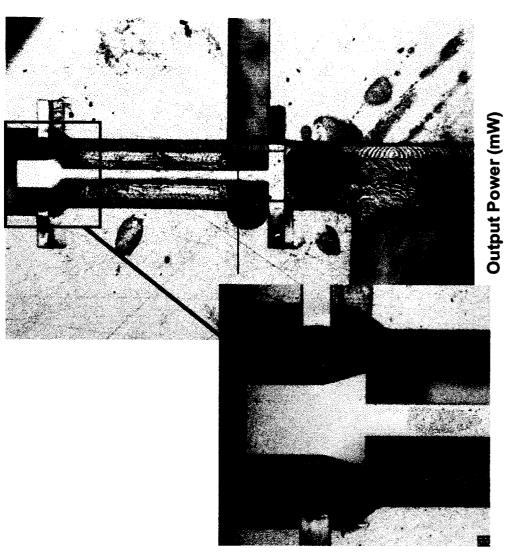
Substrateless 400 GHz Doubler in Block



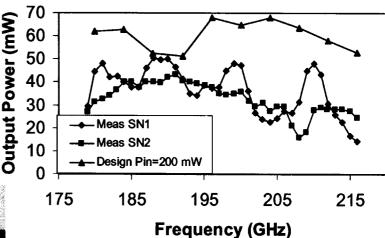




Measured Performance of 200 GHz Doubler



200 GHz Doubler Performance

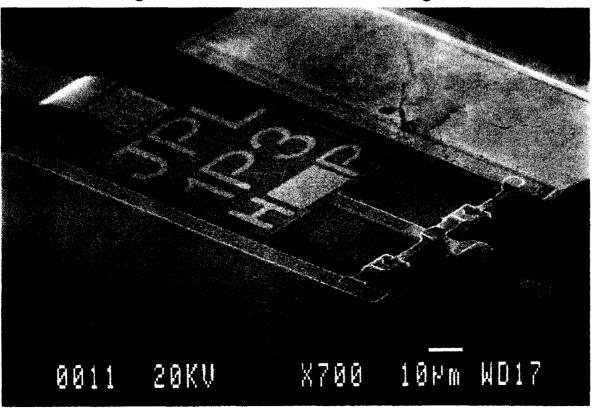






1200 GHz tripler device before mounting in a split-wave guide block

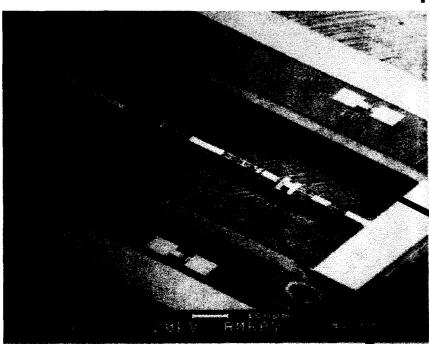
- a 3 µm thick GaAs membrane is suspended across a channel in the block
- Elimination of any thick GaAs support structure
- Two large beam leads provide the mechanical support and ground contacts to the block
- Two narrow beamleads act as RF probes in the input and output waveguides
- A similar configuration has been used in the design of a 2400 GHz doubler chip







MoMeD circuit with a planar GaAs Schottky-diode



Variations on first mask set:

- single and balanced antiparallel diodes
- position of diode in output waveguide
- length of anode finger
- anode area
- position of RF-short 0μm and 95μm
- square and tapered pads for diode

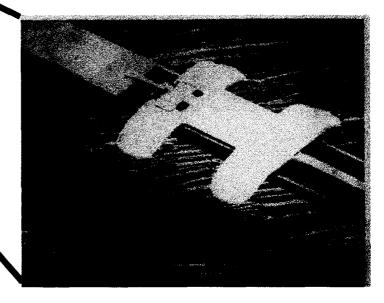
GaAs Membrane Parameters:

Length=600μm, width=30μm, thickness=3μm

Schottky Diode parameters:

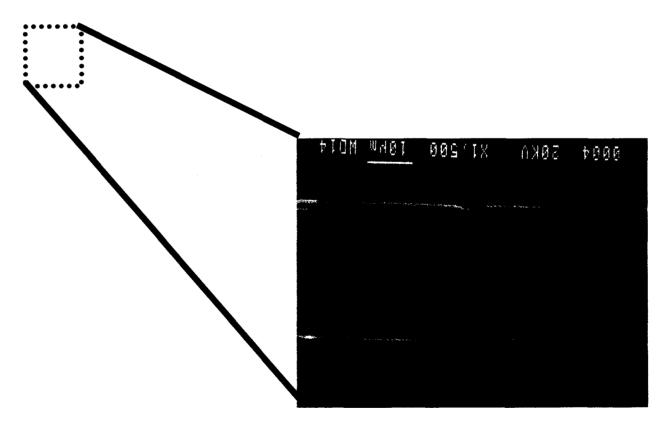
Anode dimensions: 0.4 x 1.9 µm

 $N_e = 5 \times 10^{17} / \text{cm}^3 \text{ R}_s \sim 10 \text{ Ohm } C_i < 2 \text{ fF} \quad \eta = 1.5$



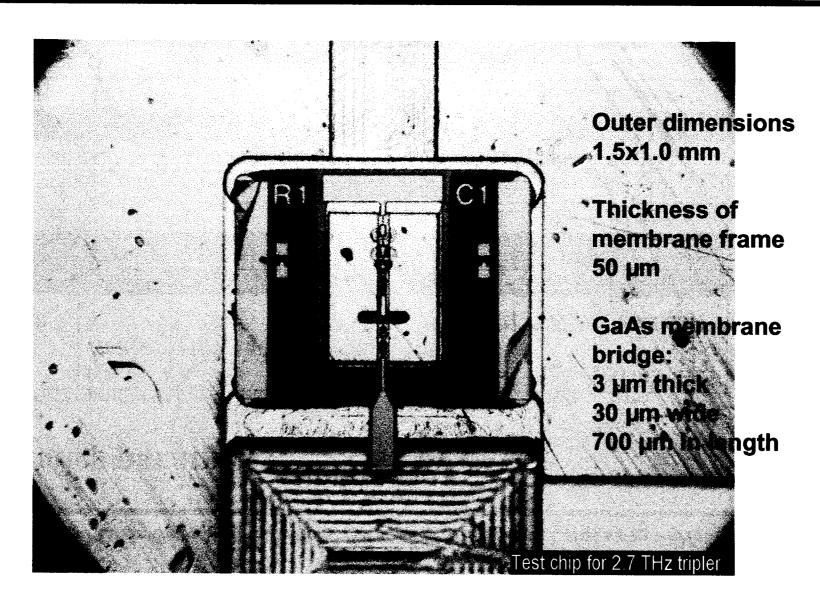
















Diodes parameter

Table 2: Diode parameters for low frequency and high frequency process multiplier diodes in use at JPL.

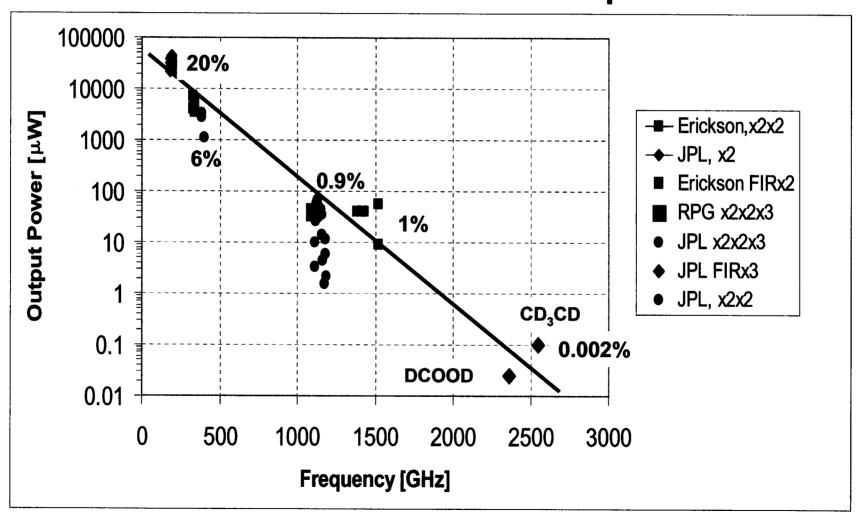
F	No. of diodes	n [10 ¹⁷ /cm ³]	Isat	Vbr	Rs	Cj0	Anode area	Imax
[GHz]	#	[20 / 0.22]	[10 ⁻¹⁵ *A]	[V]	[Ω]	[fF]	[um x um]	[mA]
400 ver2	2	4	0.19	5	12	10.5	3.1x1.5	4.7
800 ver1	1	2	0.038	8	43	2.64	1.5x1.0	1.5
800 ver2	1	4	0.038	5	43	2.64	1.1x1.0	1.1
1500	1	5	2.8	4.7	240	0.5	0.7x0.2	0.14
1600	1	5	2.8	4.7	240	0.5	0.7x0.2	0.14
1900	1	5	1.6	4.7	400	0.3	0.4x0.2	0.08

n=doping, Isat=saturation current, Vbr=breakdown voltage, Rs=series resistor, Imax=maximal current thru the diode area





Recent Results for solid state multiplier chains







Publications:

Erich Schlecht, Goutam Chattopadhyay, Alain Maestrini, David Pukala, John Gill, Suzanne Martin*, Frank Maiwald and Imran Mehdi, "A High-Power Wideband Cryogenic 200 GHz Schottky
"Substrateless" Multiplier: Modeling, Design and Results", Ninth International Conference on Terahertz Electronics
October 14-15, 2001

E. Schlecht, G. Ghattopadhyay, A. Maestrini, A. Fung, S. Martin, D. Pukala, J. Bruston and I. Mehdi, "200, 400 and 800 CLOS-254 & GHz Schottky Diode "Substrateless" Multipliers: Design and Results", International Microwave Symposium, May 2001.

E. Schlecht, F. Maiwald, G. Chattopadhyay, S. Martin, and I. Mehdi, "DESIGN CONSIDERATIONS FOR HEAVILY-DOPED CRYOGENIC SCHOTTKY DIODE VARACTOR MULTIPLIERS", 12th International Symposium on Space Terahertz Technology February 14-16, 2001

Frank Maiwald, Suzanne Martin, Jean Bruston, Alain Maestrini, Timothy Crawford, Peter H. Siegel, "Design and PBS - Performance of a 2.7 THz Waveguide Tripler", 12th International Symposium on Space Terahertz Technology February CLOO-248[
14-16, 2001

PAPER
CLOI-2272

J. Bruston, E. Schlecht, A. Maestrini, F. Maiwald, S.C. Martin, R.P. Smith[†], I. Mehdi, P.H. Siegel, and J. Pearson, "Development of 200 Ghz to 2.7 Thz Multiplier Chains for Submillimeter-wave Heterodyne Receivers", SPIE - CLOO-6373 International Symposium on Astronomical Telescopes and Instrumentation, 29 March 2000

Suzanne Martin, Barbara Nakamura, Andy Fung, Peter Smith[†], Jean Bruston, Alain Maestrini, Frank Maiwald, Peter Siegel, Erich Schlecht, and Imran Mehdi, "Fabrication of 200 to 2700 GHz Multiplier Devices using GaAs and Metal CL 60 - 2546 Membranes", IEEE MTT-S International Microwave Symposium, Phoenix, Arizona, May 20-25, 2001